



PATENT

ATTORNEY DOCKET NO.: AGX-37

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application )  
Shooshtarian, et al. )  
Serial No.: 09/527,873 )  
Filed: March 17, 2000 )  
Title: Localized Heating and )  
Cooling of Substrates )

Examiner: Hsein-Ming Lee

Art Unit: 2823

Dept. Acct. No.: 04-1403

#9  
Letter  
FJONES  
5-1-01

Commissioner for Patents  
Washington, D.C. 20231

LETTER

Dear Sir:

In regard to the Information Disclosure Statement filed herewith, the following is a co-owned patent application that may relate to the subject matter of the present application (copy of which is included herewith).

U.S. Patent Application Serial No. 09/197,284 entitled "FAST HEATING AND COOLING APPARATUS FOR SEMICONDUCTOR WAFERS"

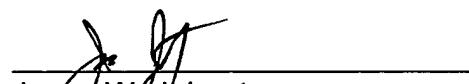
In addition, Applicants believe that the relevance of JP 59275987 and JP 02301173, which are included with the Information Disclosure Statement submitted herewith, can be readily ascertained from the Abstract and figures of each reference.

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Respectfully submitted,

DORITY & MANNING, P.A

  
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